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LF131 Ag Conductor Composition

Thick Film Composition Data Sheet

All values reported here are results of experiments in our laboratories intended to illustrate product performance potential with a given experimental design. They are not intended to represent the product's specifications, details of which are available upon demand.

Product Description

LF131 Ag conductor composition is intended to be applied to ceramic substrates by screen printing and firing in a conveyor furnace in an air (oxidizing) atmosphere. It has been developed to form interconnection tracks and pads for component and lead attachment, in hybrid microcircuits and networks.

Key Features :

- Fine line resolution
- Pb, Cd and NiO free
- Excellent solderability and adhesion with Pb-free solders
- Compatible, sequentially fired with LF151/3 dielectric as a crossover or inner layer conductor.

Compatibility

Whilst DuPont has tested this composition with the materials specified above and the recommended processing conditions, it is impossible or impractical to cover every combination of materials, customer processing conditions and circuit layouts.

It is therefore essential that customers thoroughly evaluate the material in their specific situations in order to completely satisfy themselves with the overall quality and suitability of the composition for its intended application(s).

Composition Properties

Viscosity [Pa.s]	85-145
Brookfield HBT, Utility cup & spindle (SC4-14/6R), 10 rpm, 25°C ± 0.2°C	
Coverage [cm²/g]*	≈80
Based on fired thickness of 13µm	
Shrinkage [%]	
Dry to Fired	≈36
Thinner	4553
Shelf Life [months]	6

Processing Conditions

Printing	Use 200-325 mesh stainless steel with 8 -12µm emulsion build-up. Print speeds up to 20cm/s
Drying	Allow prints to level for 5 - 10 minutes at room temperature, then dry for 10-15 minutes at 150°C
Firing	850°C peak held for 10 minutes on 30 minute cycle in an air atmosphere

Typical Fired Properties

Mean fired thick [µm]		
200 mesh stainless steel	11-15	Typically 13
325 mesh stainless steel	7-11	Typically 9
Resistivity [mΩ/□ @ 13µm]		>2.5
Soldered Adhesion¹		
Initial (N)		>20
Aged (1000hrs@ 150°C)		>18
¹ 90° wire peel test on 2mm x 2mm pad soldered with 95.5 Sn / 3.8 Ag / 0.7 Cu Solder using mildly activated flux, Alpha 611 on Alumina. LF131 is recommended for use on dielectric only for crossover and inner layer applications.		

Recommended Processing Procedure Storage

Containers may be stored in a clean, stable environment at room temperature (5-30°C), with their lids tightly sealed. Storage in freezers (temperature < 0°C) is NOT recommended as this could

cause irreversible changes in the material.

For guidance regarding storage of material, please consult DuPont Technical Note EUT 7.2 "Shelf Life Policy".

Shelf life

This composition's shelf life is from date of shipment for factory-sealed (unopened) containers, stored under room-temperature conditions. Refer to table - for shelf life

Substrates

Substrates of different compositions and from various manufacturers may result in variations in performance properties.

Thinner

This composition is optimized for screen printing, thinning is not normally required.

Use the DuPont recommended thinner for slight adjustments to viscosity or to replace evaporation losses. The use of too much thinner or the use of a non recommended thinner may affect the rheological behaviour of the material and its printing characteristics. Refer to table - "Composition Properties"

Printing

The composition should be thoroughly mixed before use. This is best achieved by slow, gentle, hand stirring with a clean burr-free spatula (flexible plastic or stainless steel) for 1-2 minutes. Care must be taken to avoid air entrapment. Printing should be performed in a clean and well ventilated area. Additional information on requirements for printing areas is contained in DuPont Technical Guide EUT 7.3 "Processing - Screen Printing Rooms", available on request.

Note: optimum printing characteristics are generally achieved in the room temperature range of 20°C-23°C. It is therefore important that the material, in its container, is at this temperature prior to commencement of printing. Class 10,000 printing area is recommended for building complex hybrids and multilayer circuits, otherwise severe yield losses could occur. Refer to table - "Processing Conditions"

Printing design

Excellent line definition can be achieved with LF131 using a standard 325 mesh, 8-12µm emulsion. The line resolution is 175µm lines/spaces on alumina, 200µm lines/spaces, sequentially fired on dielectric LF151/3.

Drying

Allow prints to level at room temperature, then dry in a well ventilated oven or conveyor dryer. Refer to table - "Processing Conditions"

Firing

Fire in a well ventilated belt, conveyor furnace, or static furnace. Air flows and extraction rates should be optimized to ensure that oxidizing conditions exist within the muffle, and that no exhaust gases enter the room. Full information on requirements for firing is contained in DuPont Technical Guide EUT 7.4 "Process Guide - Firing". Refer to table - "Processing Conditions"

General

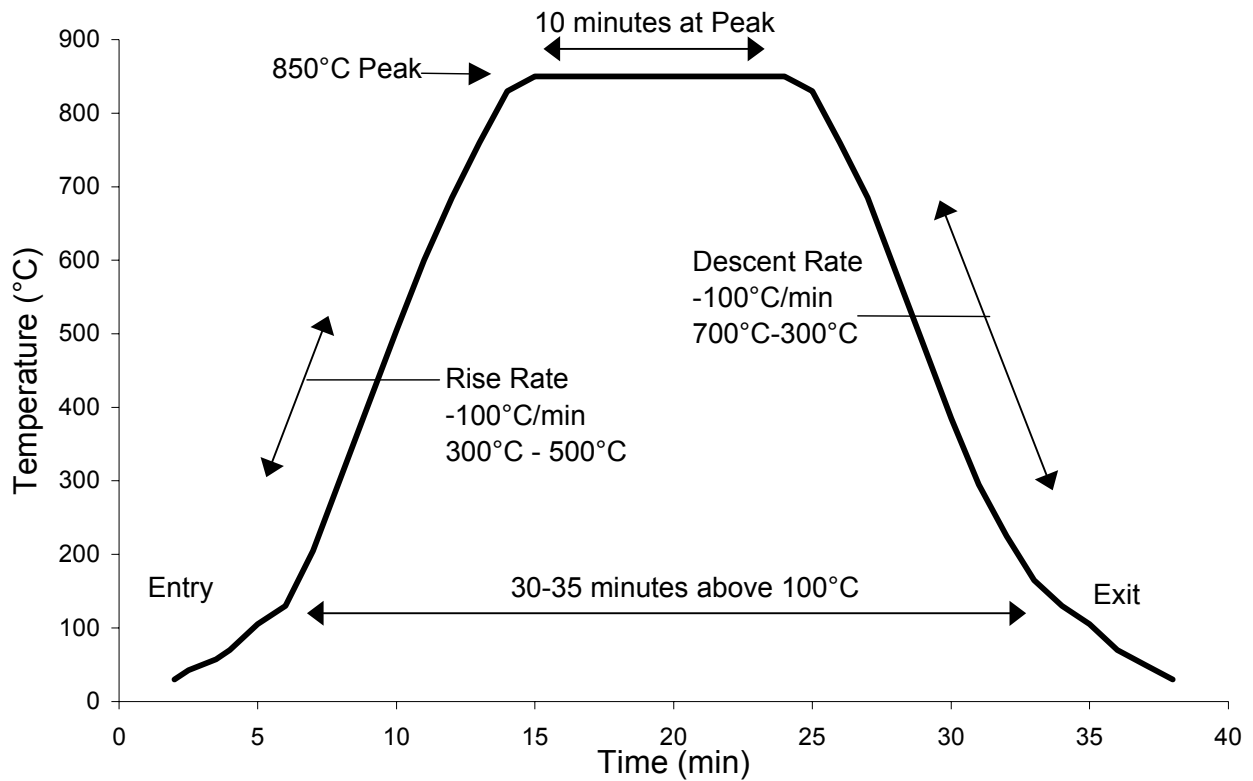
Performance will depend to a large

degree on care exercised in screen printing. Scrupulous care should be taken to keep the composition, printing screens and other tools free of metal contamination. Dust, lint and other particulate matter may also contribute to poor yields.

Health/Safety considerations

DuPont thick film compositions are intended for use in an industrial environment by trained personnel. All appropriate health / safety regulations regarding storage, handling and processing of such materials should be complied with. For information on health / safety regulations please refer to the specific product MSDS and to the DuPont Safety Guide EUT 7.1 "Practical Safe Handling of Thick Film Compositions".

Typical 850°C 30 Minute Firing Profile



This information corresponds to our current knowledge on the subject. It is offered solely to provide possible suggestions for your own experimentation. It is not intended, however, to substitute for any testing you may need to conduct to determine for yourself the suitability of our products for your particular purposes. This information may be subject to revision as new knowledge and experience become available. Since we cannot anticipate all variations in actual end-use conditions, DuPont makes no warranties and assumes no liability in connection with any use of this information. Nothing in this publication is to be considered as a license to operate under or a recommendation to infringe any patent right. **Caution: Do not use in medical applications involving permanent implantation in the human body. For other medical applications, see "DuPont Medical Caution Statement" H-50102.**